

IN THE SPECIFICATION:

Please amend the specification as follows:

Please amend paragraph [0001] as follows:

[0001] This application is related to pending United States patent application serial no. 10/705,201, entitled "Processing System and Method for Treating a Substrate", filed on November 12, 2003, now U.S. Patent 7,029,536; pending United States patent application serial no. 10/705,200, entitled "Processing System and Method for Chemically Treating a Substrate", filed on November 12, 2003, now U.S. Patent 6,951,821; pending United States patent application serial no. 10/704,969, entitled "Processing System and Method for Thermally Treating a Substrate", filed on November 12, 2003; pending United States patent application serial no. 10/705,397, entitled "Method and Apparatus for Thermally Insulating Adjacent Temperature Controlled Chambers", filed on November 12, 2003; pending United States patent application serial no. 10/~~XXX,XXX~~ 812,347, entitled "Processing System and Method For Treating a Substrate", ~~Attorney docket no. P071469-0307558/ES-038~~, filed on even date herewith; and pending United States patent application serial no. 10/~~XXX,XXX~~ 812,355, entitled "Method and System For Adjusting a Chemical Oxide Removal Process Using Partial Pressure", ~~Attorney docket no. P071469-0307699/ES-040~~, filed on even date herewith. The entire contents of all of those applications are herein incorporated by reference in their entirety.